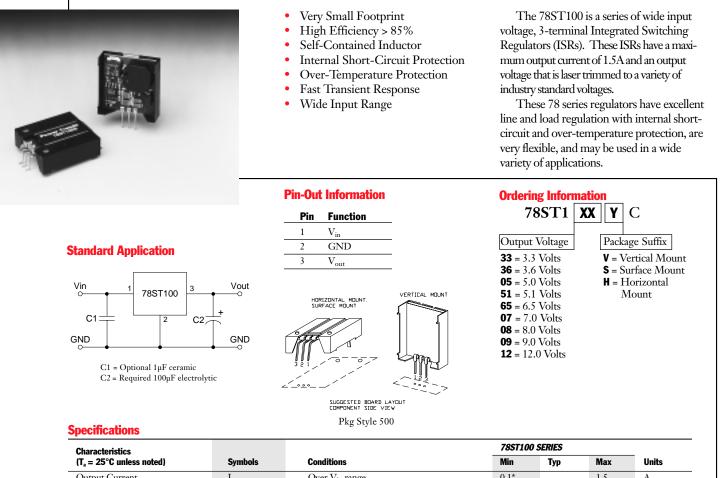
For assistance or to order; call (800) 531-5782

78ST100 Series

1.5 AMP POSITIVE STEP-DOWN INTEGRATED SWITCHING REGULATOR

Revised 6/30/98



		7851100			
Symbols	Conditions	Min	Тур	Max	Units
Io	Over V _{in} range	0.1*	_	1.5	Α
I _{sc}	V _{in} = V _{in} min		3.5	_	Apk
V_{in}	$0.1 \le I_o \le 1.5A$ $V_o = 3.3V$ $V_o = 5V$ $V_o = 12V$	7 7 14.5	=	26 30 30	$egin{array}{c} V \\ V \\ V \end{array}$
ΔV_{o}	Over V_{in} range, $I_o=1.5A$ $T_a = 0^{\circ}C$ to +60°C	_	±1.0	±2.0	%V _o
Reg _{line}	Over V _{in} range	_	±0.2	±0.4	%Vo
	$0.1 \le I_o \le 1.5 A$	_	±0.1	±0.2	%Vo
V_n	V_{in} = 9V, I_o = 1.5A V_o = 5V V_{in} = 16V, I_o = 1.5A V_o = 12V	—	65 90	—	${}^{ m mV_{pp}}_{ m mV_{pp}}$
t _{tr}	50% load change V_0 over/undershoot	_	100 5	_	μSec %Vo
η	$\begin{array}{lll} V_{in} = 10V, I_o = 1A & V_o = 3.3V \\ V_{in} = 10V, I_o = 1A & V_o = 5V \\ V_{in} = 17V, I_o = 1A & V_o = 12V \end{array}$		80 85 90		% % %
f_{o}	Over V _{in} range, I _o =1.5A	600	650	700	kHz
Та	-	-40	-	+85	°C
Та	Free Air Convection, (40-60LFM) At V _{in} = 24V, I _o =1.0A	-40	_	+80**	°C
θ_{ja}	Free Air Convection, (40-60LFM)	_	45		°C/W
T _s	—	-40	_	+125	°C
_	Per Mil-STD-883D, Method 2002.3	_	500	_	G's
—	Per Mil-STD-883D, Method 2007.2, 20-2000 Hz, soldered in a PC board	_	5	—	G's
_	_	_	6.5	_	grams
	I_{o} I_{sc} V_{in} ΔV_{o} Reg_{line} Reg_{load} V_{n} t_{tr} η f_{o} T_{a} θ_{ja}	$\begin{array}{c c c c c c c c c c c c c c c c c c c $			$\begin{array}{c c c c c c c c c c c c c c c c c c c $

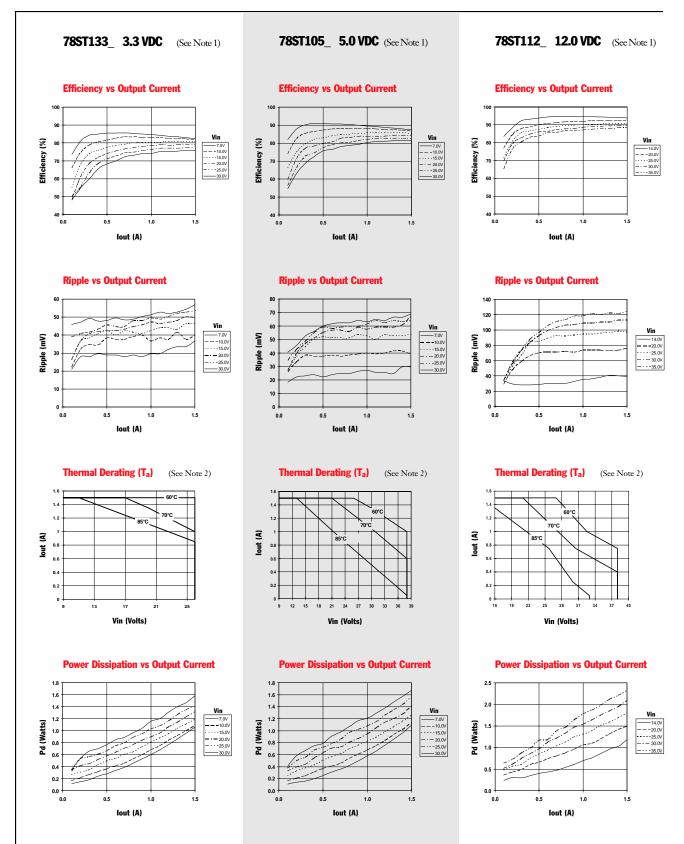
*ISR will operate down to no load with reduced specifications. **See Thermal Derating chart.

Note: The 78ST100 Series requires a 100µF electrolytic or tantalum output capacitor for proper operation in all applications.

e s

CHARACTERISTIC DATA

78ST100



Note 1: All data listed in the above graphs, except for derating data, bas been developed from actual products tested at 25°C. This data is considered typical data for the ISR. Note 2: Thermal derating graphs are developed in free air convection cooling of 40-60 LFM. (See Thermal Application Notes.)

6-Dec-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
78ST105HC	NRND	SIP MOD ULE	EFA	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
78ST105SC	NRND	SIP MOD ULE	EFC	3	25	Pb-Free (RoHS)	Call TI	Level-1-215C-UNLIM
78ST105SCT	OBSOLETE	SIP MOD ULE	EFC	3		TBD	Call TI	Call TI
78ST105VC	NRND	SIP MOD ULE	EFD	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
78ST107HC	OBSOLETE	SIP MOD ULE	EFA	3		TBD	Call TI	Call TI
78ST107SC	OBSOLETE	SIP MOD ULE	EFC	3		TBD	Call TI	Call TI
78ST107SCT	OBSOLETE	SIP MOD ULE	EFC	3		TBD	Call TI	Call TI
78ST107VC	OBSOLETE	SIP MOD ULE	EFD	3		TBD	Call TI	Call TI
78ST108HC	OBSOLETE	SIP MOD ULE	EFA	3		TBD	Call TI	Call TI
78ST108SC	OBSOLETE	SIP MOD ULE	EFC	3		TBD	Call TI	Call TI
78ST108SCT	OBSOLETE	SIP MOD ULE	EFC	3		TBD	Call TI	Call TI
78ST108VC	OBSOLETE	SIP MOD ULE	EFD	3		TBD	Call TI	Call TI
78ST109HC	NRND	SIP MOD ULE	EFA	3	25	TBD	Call TI	Level-1-215C-UNLIM
78ST109SC	NRND	SIP MOD ULE	EFC	3		TBD	Call TI	Call TI
78ST109SCT	OBSOLETE	SIP MOD ULE	EFC	3		TBD	Call TI	Call TI
78ST109TC	OBSOLETE	SIP MOD ULE	EFT	3		TBD	Call TI	Call TI
78ST109VC	NRND	SIP MOD ULE	EFD	3	25	TBD	Call TI	Level-1-215C-UNLIM
78ST112HC	NRND	SIP MOD ULE	EFA	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
78ST112SC	NRND	SIP MOD ULE	EFC	3	25	Pb-Free (RoHS)	Call TI	Level-1-215C-UNLIM
78ST112SCT	OBSOLETE	SIP MOD ULE	EFC	3		TBD	Call TI	Call TI
78ST112TC	NRND	SIP MOD ULE	EFT	3	25	Pb-Free (RoHS)	Call TI	Level-1-215C-UNLIM
78ST112VC	NRND	SIP MOD ULE	EFD	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
78ST133HC	NRND	SIP MOD ULE	EFA	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
78ST133SC	NRND	SIP MOD ULE	EFC	3	25	Pb-Free (RoHS)	Call TI	Level-1-215C-UNLIM
78ST133SCT	OBSOLETE	SIP MOD ULE	EFC	3		TBD	Call TI	Call TI

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
78ST133VC	NRND	SIP MOD ULE	EFD	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
78ST136HC	NRND	SIP MOD ULE	EFA	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
78ST136SC	OBSOLETE	SIP MOD ULE	EFC	3		TBD	Call TI	Call TI
78ST136SCT	OBSOLETE	SIP MOD ULE	EFC	3		TBD	Call TI	Call TI
78ST136VC	OBSOLETE	SIP MOD ULE	EFD	3		TBD	Call TI	Call TI
78ST151HC	OBSOLETE	SIP MOD ULE	EFA	3		TBD	Call TI	Call TI
78ST151SC	OBSOLETE	SIP MOD ULE	EFC	3		TBD	Call TI	Call TI
78ST151SCT	OBSOLETE	SIP MOD ULE	EFC	3		TBD	Call TI	Call TI
78ST151VC	OBSOLETE	SIP MOD ULE	EFD	3		TBD	Call TI	Call TI
78ST165HC	NRND	SIP MOD ULE	EFA	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
78ST165SC	NRND	SIP MOD ULE	EFC	3	25	Pb-Free (RoHS)	Call TI	Level-1-215C-UNLIM
78ST165SCT	OBSOLETE	SIP MOD ULE	EFC	3		TBD	Call TI	Call TI
78ST165VC	NRND	SIP MOD ULE	EFD	3		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.



In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
Low Power Wireless	www.ti.com/lpw	Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address:

Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2006, Texas Instruments Incorporated